



MULTILAYER CERAMIC CAPACITORS

Low Profile Series

0402 to 1210 Sizes

X7R, X5R & Y5V Dielectrics

Halogen Free & RoHS Compliance



*Contents in this sheet are subject to change without prior notice.

ASC_Low Profile_(TT)_009Q_AS

Dec. 2018



1. DESCRIPTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

WTC TT series MLCC is used in product having thickness concerned generally have high capacitance and thinner product thickness. The high dielectric constant material X7R, X5R and Y5V are used for this series product.

2. FEATURES

- a. Standard size with thin thickness.
- b. Small size with high capacitance.
- c. Capacitor with lead-free termination (pure Tin).

3. APPLICATIONS

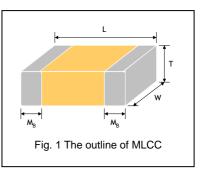
- a. For LCD panels.
- b. For PCMCA cards.
- c. For IC packaging and modules.
- d. Any thickness concerned products.

4. HOW TO ORDER

TT	<u>15</u>	<u>X</u>	<u>475</u>	M	<u>6R3</u>	<u>C</u>	Ī
<u>Series</u>	<u>Size</u>	<u>Dielectric</u>	Capacitance	Tolerance	Rated voltage	Termination	Packaging
TT =Low profile	15 =0402 (1005)	B =X7R	Two significant	K =±10%	Two significant	C =Cu/Ni/Sn	T =7" reeled
·	18 =0603 (1608)	X=X5R +	digits followed by	M=±20%	digits followed by		G=13" reeled
	21 =0805 (2012)	F=Y5V	no. of zeros. And	Z =-20/+80%	no. of zeros. And		
	31 =1206 (3216)		R is in place of		R is in place of		
	32 =1210 (3225)		decimal point.	5A	decimal point.		
		8	PASSIVE SYS	TEM ALLIANCE	6R3=6.3 VDC		
		PAR	475=47x10 ⁵		100=10 VDC		
		E.	=4,700,000pF		160=16 VDC		
		Ć	₽ =4.7μF	0	250=25 VDC		
			Cho Cho	01	500=50 VDC		
			SA TRAINING	UB1	101=100 VDC		
			- CANOLOGY	CORPORATION			

5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		M _B (mm)
0402 (1005)	1.00±0.2	0.5±0.2	0.30±0.03	L	0.25±0.10
0603 (1608)	1.6+0.15/-0.10	0.8+0.15/-0.10	0.50±0.10	Н	0.40±0.15
0805 (2012)	2.00±0.20	1.25±0.20	0.85±0.10	т	0.50±0.20
1006 (2016)	2 20 . 0 20	1 60 . 0 20	0.85±0.10	Т	0.60.0.20
1206 (3216)	3.20±0.20	1.60±0.20	1.15±0.15	J	0.60±0.20
1010 (2005)	3.20±0.30	2 50 . 0 20	0.85±0.10	Т	0.75.0.25
1210 (3225)	3.20±0.30	2.50±0.20	2.00±0.20	К	0.75±0.25



Approval Sheet

* Reflow soldering process only is recommended.

6. GENERAL ELECTRICAL DATA

Dielectric	X7R	X5R	Y5V
Size			
Capacitance range*	1µF to 10µF	0.22µF to 22µF	1μF to 10μF
Capacitance tolerance**	K (±10%), M (±20%)	Z (-20/+80%)
Rated voltage (WVDC)	10V, 16V, 25V, 50V, 100V	6.3V, 10V, 16V, 25V	10V, 16V, 25V, 50V
Operating temperature	-55 to +125°C	-55 to +85°C	-25 to +85℃
Capacitance characteristic		15%	+30/-80%
Termination	HANT AN	Ni/Sn (lead-free termination)	

* Measured at 1.0±0.2Vrms, 1.0kHz±10%, 30~70% related humidity, 25℃ ambient temperature for X7R, X5R and at 20℃ for Y5V.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.



7. CAPACITANCE RANGE

7-1 X7R dielectric

	Dielectric						X7R					
	Size		80	05			12	06			1210	
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16	100
	1.0µF (105)							Т				
0	1.5µF (155)											
Capacitance	2.2µF (225)		Т	Т					Т			K
ita	3.3µF (335)											
Dac	4.7µF (475)	Т						Т				
a	6.8µF (685)											
J	10µF (106)					Т						
	22µF (226)											

7-2 X5R dielectric

	Dielectric									(5R								
	Size	0402 0603 0805 120			1206	206		1210										
Rate	ed voltage (VDC)	6.3	10	25	10	16	6.3	10	16	25	6.3	10	16	25	50	10	16	25
	0.22uF (224)			L	Н	Н												
	0.47uF (474)	L		L														
	1.0µF (105)	L			Н	Н		Т	Т	Т		Т	Т	Т				
e	1.5µF (155)							Т	Т			Т	Т	Т				
ano	2.2µF (225)	L					T T	T	T	T		Т	Т	Т	Т			
Capacitance	3.3µF (335)					15	211	7		1		Т	Т	Т		Т		
apa	4.7µF (475)	L			Н	. KK	Ť	nÆ /	T	A.		Т	Т	Т		Т		
ő	6.8µF (685)				14		FY .	收1	ゴふ		21							
	10µF (106)				45	N. 4	$\times \tau$	Т	$\neg \tau $	IS S	×0,5	J/T		Т		Т		Т
	22uF (226)				HHIT		Т	Т		<f -<="" th=""><th>τ)</th><th>31</th><th>Т</th><th></th><th></th><th></th><th>Т</th><th></th></f>	τ)	31	Т				Т	
	47uF (476)				77						(т)							

7-3 Y5V dielectric

	Dielectric		Y5V								
	Size		08	305			12	06		12	10
Rate	ed voltage (VDC)	10	16	25	50	10	16	25	50	10	16
	1.0µF (105)			O	T			\$			
	1.5µF (155)			MAI	Prh.	(014.0	5			
ů,	2.2µF (225)		T	12.S/A		DIOEN)	T	Т	Т		
ital	3.3µF (335)	Т			LOHNING		TION .				
Capacitance	4.7µF (475)	Т	Т		- MOLU	3 LAKKON	T				
a l	6.8µF (685)					Т					
	10µF (106)	Т				Т				Т	
	22µF (226)										

PSA

8. PACKAGING STYLE AND QUANTITY

Sino	Thickness Max (mm)		7" reel			
Size	Thickness Max (mm)	<i>y</i> /Symbol	Paper tape	Plastic tape		
0402 (1005)	0.33	L	15k	-		
0603 (1608)	0.60	Н	4k	-		
0805 (2012)	0.95	Т	4k	-		
4000 (0040)	0.95	Т	4k	-		
1206 (3216)	1.30	J	-	3k		
1210 (2225)	0.95	Т	-	3k		
1210 (3225)	2.00	к	-	1k		

Unit: pieces

ASC_Low Profile_(TT)_009Q_AS





9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements
	Visual and Mechanical		* No remarkable defect. * Dimensions to conform to individual specification sheet.
-	Capacitance Q/ D.F. (Dissipation Factor)	Cap≤10µF, 1.0±0.2Vrms, 1kHz±10% Cap>10µF, 0.5±0.2Vrms, 120Hz±20%** ** Test condition: 0.5±0.2Vrms → 1KHz±10% TT18X≧475(10V) , TT15X series *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp .	* Shall not exceed the limits given in the detailed spec. X7R/X5R: Rated vol. D.F. 100V ≤5% 50V, 25V, 16V, 10V ≤10% 6.3V ≤15% Y5V: Rated vol. D.F. 50V ≤7% 25V ≤9% 16V/10V ≤12.5%
	Dielectric Strength	 To apply voltage: 250% rated voltage. Duration: 1 to 5 sec. Charge and discharge current less than 50mA. 	* No evidence of damage or flash over during test.
	Insulation Resistance	* To apply rated voltage for max. 120 sec.	≥10GΩ or RxC≥100Ω-F whichever is smaller.
6.	Temperature Coefficient	With no electrical load. T.C. Operating Temp X7R -55~125°C at 25°C X5R -55~85°C at 25°C Y5V -25~85°C at 20°C *Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24± 2 hrs at room temp.	T.C.Capacitance ChangeX7RWithin ±15%X5RWithin ±15%Y5VWithin +30%/-80%
		$\begin{array}{c c c c c c c c c c c c c c c c c c c $	
7.	Adhesive Strength of	* Pressurizing force : 5N (≤0603) and 10N (>0603) * Test time: 10±1 sec.	* No remarkable damage or removal of the terminations.
•	Termination	* Vibration frequency: 10~55 Hz/min.	
8.	Vibration Resistance	* Total amplitude: 1.5mm * Total amplitude: 1.5mm * Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24± 2 hrs at room temp. * Cap./DF(Q) Measurement to be made after de-aging at 150°C for 1hr then set for 24±2 hrs at room temp.	 No remarkable damage. * Cap change and Q/D.F.: To meet initial spec.
9.	Solderability	* Solder temperature: 235±5℃	95% min. coverage of all metalized area.
10.	Bending Test	 Dipping time: 2±0.5 sec. The middle part of substrate shall be pressurized by means of the pressuriging rod at a rate of about 1 mm per second un the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec. Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs. 	til. * Can change :
11.	Resistance to Soldering Heat	 * Solder temperature: 260±5℃ * Dipping time: 10±1 sec * Preheating: 120 to 150℃ for 1 minute before imme rse the capacitor in a eutectic solder. *Before initial measurement (Class II only): To apply de-aging at 150℃ for 1hr then set for 24±2 hrs at room temp . *Cap. / DF(Q) / I.R. Measurement to be made after de-aging 150℃ for 1hr then set for 24±2 hrs at room temp. 	* $O/D \in I R$ and dielectric strength: To meet initial requirements

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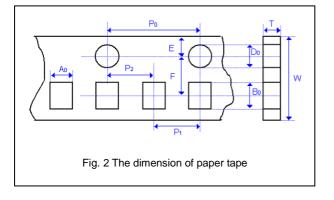
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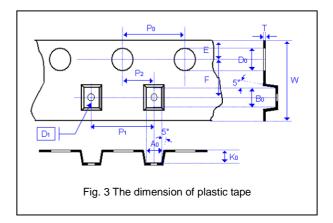


No.	ltem		Test Conditio	n		Requiren	nents
12.	Temperature	* Conduc	the five cycles according to the	ne temperatures and	* No remarkable	damage.	
	Cycle	time.			* Cap change :		
		Step	Temp. (°C)	Time (min.)	X7R/X5R: with	in ±7.5%	
		1	Min. operating temp. +0/-3	30±3	Y5V: within ±20	0%	
		2	Room temp.	2~3	* Q/D.F., I.R. and	d dielectric strength:	To meet initial requirements.
		3	Max. operating temp. +3/-0	30±3	, ,	<u> </u>	
		4	Room temp.	2~3			
		* Before i	nitial measurement (Class II or	nly): To apply de-aging			
		at 150℃ f	or 1hr then set for 24±2 hrs at	room temp.			
		* Cap. / D	F(Q) / I.R. Measurement to be	e made after de-aging			
		at 150℃ f	or 1hr then set for 24±2 hrs at	room temp.			
13.	Humidity	* Test terr	ıp.: 40±2℃		*No remarkable	damage. X7R/X5R: within ±25	. 0/_
	(Damp Heat)	* Humidity	/: 90~95% RH			Y5V: within ±30%; 6.	
	Steady State	* Test time	e: 500+24/-0hrs.		*Q/D.F. value:		
		* Before i	nitial measurement (Class II or	nly): To apply de-aging	X7R/X5R:		
		at 150℃ f	or 1hr then set for 24±2 hrs at	room temp.	Rated vol.	D.F.	
		* Cap. / D	F(Q) / I.R. Measurement to be	e made after de-aging	100V	≤7.5%	
		at 150℃ f	or 1hr then set for 24±2 hrs at	room temp.	25V, 16V	≤15%	
					10V	≤20%	
					50V, 6.3V	≤30%	
				水石	Y5V:	DE	
			145	PTH /	Rated vol. 50V	D.F. ≤10%	_
				上阳化	25V	≤15%	
				<u>LVXV</u> Z	16V, 10V	≤20%	
			tillow La			Y	a amallar
4.4		<u> </u>			*No remarkable	C≩10 Ω-F whichever i damage.	s smaller.
14.	Humidity		p.: 40±2℃		*Cap change: 2	X7R/X5R: within ±25	
	(Damp Heat)		/: 90~95%RH			Y5V: within ±30%; 6	.3V, within +30/-40%
	Load	1	e: 500+24/-0 hrs.	SSTVE SYSTEM AL	*Q/D.F. value:		
			voltage : Rated voltage.		X7R/X5R:	E	
			nitial measurement (Class II or or 1hr then set for 24±2 hrs at		Rated vol.	D.F.	
		1			100V S	≤7.5%	
			F(Q) / I.R. Measurement to be		25V, 16V	≤15%	
		al 150°C	for 1hr then set for 24±2 hrs a	it room temp.	10V	≤20%	
			SAL SAL	VIOIOgy Y	50V, 6.3V	≤30%	
				CHNDIACY CODDOR	Y5V:		
				UCLUGY LUKPUN	Rated vol.	D.F.	
					50V	≤10%	
					25V	≤15%	
					16V, 10V	≤20%	
		<u> </u>	- '		-	$RxC \ge 5 \Omega$ -F whichev	er is smaller.
4.5			μ		*No remarkable of	•	0/
15.	High	* Test tem NP0, X7			1 · · · · · · · · · · · · · · · · · · ·	V7D/VED: within 19E	
15.	High Temperature	NP0, X7	R/X7E: 125±3℃ V: 85±3℃		*Cap change: 2	X7R/X5R: within ±25 Y5V: within ±30%; 6	
15.		NP0, X7 X5R, Y5 * Test time	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs.		*Cap change: 2		3V, within +30/-40%
15.	Temperature	NP0, X7 X5R, Y5 * Test time * To apply	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs. v voltage: 150% of rated voltag		*Cap change:		
15.	Temperature Load	NP0, X7 X5R, Y5 * Test time * To apply **100% o	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs. : voltage: 150% of rated voltag f rated voltage for below range	2.	*Cap change: *Q/D.F. value: X7R/X5R:	Y5V: within ±30%; 6	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test time * To apply	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs. v voltage: 150% of rated voltag		*Cap change: > *Q/D.F. value:		
15.	Temperature Load	NP0, X7 X5R, Y5 * Test time * To apply **100% o Size TT15	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs. voltage: 150% of rated voltag f rated voltage for below range Dielectric Rated voltage X5R 6.3V	o. Capacitance range C≧1.0µF	*Cap change:) *Q/D.F. value: X7R/X5R: Rated vol.	Y5V: within ±30%; 6.	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test time * To apply **100% o Size	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs. voltage: 150% of rated voltag f rated voltage for below range Dielectric Rated voltage X5R 6.3V Y5V 6.3V,10V	Capacitance range C≥1.0µF C≥2.2µF	*Cap change: > *Q/D.F. value: X7R/X5R: Rated vol. 100V	Y5V: within ±30%; 6. D.F. ≤7.5%	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test time * To apply **100% o Size TT15	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs. voltage: 150% of rated voltag f rated voltage for below range Dielectric Rated voltage X5R 6.3V Y5V 6.3V,10V Y5V 6.3V	Capacitance range $C \ge 1.0\mu F$ $C \ge 2.2\mu F$ $C \ge 10\mu F$	*Cap change: *Q/D.F. value: X7R/X5R: Rated vol. 100V 25V, 16V	Y5V: within ±30%; 6. D.F. ≤7.5% ≤15%	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test time * To apply **100% o Size TT15 TT18	R/X7E: 125±3℃ V: 85±3℃ e: 1000+24/-0 hrs. voltage: 150% of rated voltag f rated voltage for below range Dielectric Rated voltage X5R 6.3V Y5V 6.3V,10V	Capacitance range C≥1.0µF C≥2.2µF	*Cap change: *Q/D.F. value: X7R/X5R: Rated vol. 100V 25V, 16V 10V	Y5V: within ±30%; 6. □ D.F. □ ≤7.5% □ ≤15% □ ≤20%	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test time * To apply **100% o Size TT15 TT18 TT21 TT21 TT31	$\begin{array}{c c} R/X7E: 125\pm 3 \mathbb{C} \\ V: 85\pm 3 \mathbb{C} \\ a: 1000+24/\text{-}0 \text{ hrs.} \\ voltage: 150\% \text{ of rated voltage} \\ f rated voltage for below range \\ \hline \\ $	Capacitance range $C \ge 1.0 \mu F$ $C \ge 2.2 \mu F$ $C \ge 10 \mu F$ $C \ge 10 \mu F$ $C \ge 22 \mu F$	*Cap change: *Q/D.F. value: X7R/X5R: Rated vol. 100V 25V, 16V 10V 50V, 6.3V	Y5V: within ±30%; 6. □ D.F. □ ≤7.5% □ ≤15% □ ≤20%	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test tim. * To apply **100% o Size <u>TT15</u> <u>TT18</u> TT21 <u>TT31</u> *Before in	$\begin{array}{l lllllllllllllllllllllllllllllllllll$	b. Capacitance range $C \ge 1.0\mu F$ $C \ge 2.2\mu F$ $C \ge 10\mu F$ $C \ge 10\mu F$ $C \ge 22\mu F$ Idy): To apply de-aging	*Cap change: Q/D.F. value: X7R/X5R: Rated vol. 100V 25V, 16V 10V 50V, 6.3V Y5V:	Y5V: within ±30%; 6. D.F. ≤7.5% ≤15% ≤20% ≤30%	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test tim. * To apply **100% o Size <u>TT15</u> <u>TT18</u> TT21 <u>TT31</u> *Before ir at 150°C f	$\begin{array}{c} R/X7E: 125\pm 3 \mathbb{C} \\ V: 85\pm 3 \mathbb{C} \\ \mathfrak{s:} 1000\pm 24/\text{-}0 \ hrs. \\ voltage: 150\% \ of rated voltag \\ f rated voltage for below range \\ \hline \hline \\ \hline \\ \textbf{Dielectric} & \hline \\ \textbf{Rated voltage} \\ \hline \\ \hline \\ \textbf{V5V} & \textbf{6.3V} \\ \hline \\ \textbf{Y5V} & \textbf{6.3V} \\ \hline \\ \hline \\ \textbf{X5R}/X7R/X6S \\ \hline \\ \textbf{STR}/X7R/X6S \\ \hline \\ \textbf{STR}/X7R/X7R \\ \hline \\ \textbf{STR}/X7R \\ \hline \\ \hline \\ \textbf{STR}/X7R \\ \hline \\ \hline \\ \hline \\ \textbf{STR}/X7R \\ \hline \\ \hline \\ \hline \\ \textbf{STR}/X7R \\ \hline \\ $	Capacitance range $C \ge 1.0\mu F$ $C \ge 2.2\mu F$ $C \ge 10\mu F$ $C \ge 10\mu F$ $C \ge 22\mu F$ Idy): To apply de-aging room temp.	*Cap change:) *Q/D.F. value: X7R/X5R: Rated vol. 100V 25V, 16V 10V 50V, 6.3V Y5V: Rated vol.	Y5V: within ±30%; 6. D.F. ≤7.5% ≤15% ≤20% ≤30% D.F.	
15.	Temperature Load	NP0, X7 X5R, Y5 * Test tim. * To apply **100% o Size TT15 TT18 TT21 TT21 TT21 *Before ir at 150°C f * Cap. / D	$\begin{array}{l lllllllllllllllllllllllllllllllllll$	Capacitance range $C \ge 1.0\mu F$ $C \ge 2.2\mu F$ $C \ge 10\mu F$ $C \ge 10\mu F$ $C \ge 22\mu F$ ly): To apply de-aging room temp. de-aging at 150°C for	*Cap change: Q/D.F. value: X7R/X5R: Rated vol. 100V 25V, 16V 10V 50V, 6.3V Y5V: Rated vol. 50V	Y5V: within ±30%; 6. D.F. ≤7.5% ≤15% ≤20% ≤30% D.F. ≤10%	

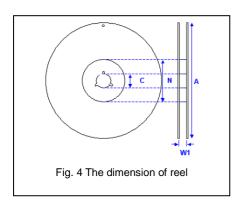
APPENDIXES

■ Tape & reel dimensions





Size	0402	0603	0805	12	06	12	:10
Thickness	L	н	T	Т	J	т	к
Ao	0.70 +/-0.2	1.05 +/-0.30	1.50 +/-0.20	1.90 +/-0.50	< 2.00	< 3.05	1.05 +/-0.30
Bo	1.20 +/-0.2	1.80 +/-0.30	2.30 +/-0.20	3.50 +/-0.50	< 3.70	< 3.80	1.80 +/-0.30
т	\leq 0.80	≦1.20	≦1.20	≦1.20	0.23 +/-0.1	0.23 +/-0.1	≦1.20
Ko	-	- 17 #	4		< 2.50	< 1.50	-
w	8.00 +/-0.30	8.00 +/-0.30	8.00	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30	8.00 +/-0.30
Po	4.00 +/-0.10	4.00 +/-0.10	PASS 4.00 SYSTEM +/-0.10	+/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
10xP₀	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20	40.00 +/-0.20
P ₁	2.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10	4.00 +/-0.10
P ₂	2.00 +/-0.05	2.00 +/-0.05	2.00	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05	2.00 +/-0.05
Do	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0	1.50 +0.1/-0
D ₁	-	-	-	-	1.00 +/-0.10	1.00 +/-0.10	-
E	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10	1.75 +/-0.10
F	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05	3.50 +/-0.05

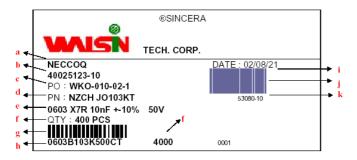


Size	0402, 0603, 0805, 1206, 1210						
Reel size	7"	10"	13"				
С	13.0+0.5/-0.2	13.0+0.5/-0.2	13.0+0.5/-0.2				
W ₁	8.4+1.5/-0	8.4+1.5/-0	8.4+1.5/-0				
Α	178.0±1.0	250.0±1.0	330.0±1.0				
N	60.0+1.0/-0	100.0±1.0	100±1.0				

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Example of customer label



*Customized label is available upon request

- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer

Approval Sheet

- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

Constructions

No.	Nan	ne	X7R, X5R, Y5V		
1	Ceramic r	naterial	BaTiO₃ based		
2	Inner ele	ctrode	派所不同 信风) >
3		Inner layer	法CLUC分本		
4	Termination	Middle layer	Ni	• • • • • • • • • • • • • • • • • • •	
5		Outer layer	Sn (Matt)	Fig. 5 The construction of MLCC	
	•				

Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)

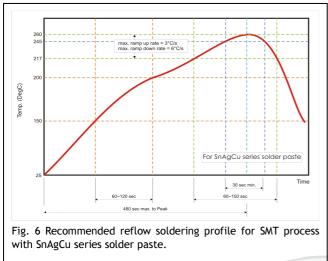
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- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.



Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.



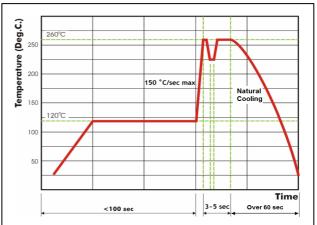


Fig. 7 Recommended wave soldering profile for SMT process with $\ensuremath{\mathsf{SnAgCu}}$ series solder.

